

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Tsutomu SATO et al.

GAU:

SERIAL NO: New Application

EXAMINER:

FILED: Herewith

FOR: SEMICONDUCTOR DEVICE FORMED IN SEMICONDUCTOR LAYER ARRANGED ON SUBSTRATE WITH ONE OF INSULATING FILM AND CAVITY INTERPOSED BETWEEN THE SUBSTRATE AND THE SEMICONDUCTOR LAYER

REQUEST FOR PRIORITY

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

- Full benefit of the filing date of U.S. Application Serial Number 10/091,448, filed March 7, 2002, is claimed pursuant to the provisions of 35 U.S.C. §120.
- Full benefit of the filing date(s) of U.S. Provisional Application(s) is claimed pursuant to the provisions of 35 U.S.C. §119(e): Application No. _____ Date Filed _____
- Applicants claim any right to priority from any earlier filed applications to which they may be entitled pursuant to the provisions of 35 U.S.C. §119, as noted below.

In the matter of the above-identified application for patent, notice is hereby given that the applicants claim as priority:

<u>COUNTRY</u>	<u>APPLICATION NUMBER</u>	<u>MONTH/DAY/YEAR</u>
Japan	2001-398184	December 27, 2001

Certified copy of the corresponding Convention Application(s)

- are submitted herewith
- will be submitted prior to payment of the Final Fee
- was filed in prior application Serial No. 10/091,448 filed March 7, 2002
- were submitted to the International Bureau in PCT Application Number Receipt of the certified copies by the International Bureau in a timely manner under PCT Rule 17.1(a) has been acknowledged as evidenced by the attached PCT/IB/304.
- (A) Application Serial No.(s) were filed in prior application Serial No. _____ filed _____ ; and
- (B) Application Serial No.(s)
 - are submitted herewith
 - will be submitted prior to payment of the Final Fee

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,
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